Number	Hits	Search Text	DB	Time stamp
1	86	soler adj ball improve with wire with bond and (257/$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 16:25
2	1	soler adj ball with improve with wire with bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 16:25
3	4	solder adj ball with improve with wire with bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 16:30
4	99	solder adj ball with wire with bond with connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 16:38
5	24	solder adj ball with wire with bond with lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 16:39
-	603	(257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 16:28
-	220	((257/691).CCLS.) and power with line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:17
-	238530	((257/691).CCLS.) and metallization with over coat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:18
-	2	((257/691).CCLS.) and metallization with overcoat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:19
-	19	((257/691).CCLS.) and metallization with (die IC semiconductor chip) with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:44
-	4	5311058.URPN.	USPAT	2002/10/17 18:23
-	5	5751067.URPN.	USPAT	2002/10/17 18:25
-	14	."5229639" "5251840" "5252853" "5252854" "5286999" "5311058" "5358204" "5359224" "5365113" "5394008" "5428247" "5442233" "5461255" "5473190").PN.	USPAT	2002/10/17 18:26
-	51	5461255.URPN.	USPAT	2002/10/17 18:32
-	766	257/737.CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:47
-	10	((257/737).CCLS.) and metallization with die IC semiconductor chip with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:47

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-	759	(257/208).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:47
-	6	257/208.CCLS. and metallization with die IC semiconductor chip with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/17 18:47
-	27	4249192.URPN.	USPAT	2002/10/17 18:49
-	4265	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 10:48
-	3066	(257/666).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 10:48
-	1059	((257/666).CCLS.) AND(metallization lead line bus) WITH (chip die ic semiconductor integrated adj circuit)WITH surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 10:52
-	842	(((257/666).CCLS.) AND(metallization lead line bus) WITH (chip die ic semiconductor integrated adj circuit)WITH surface) AND wire AND lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 10:52
-	796	((257/666).CCLS.) AND(metallization lead line bus) WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 10:53
-	30	((257/666).CCLS.) AND(metallization lead line bus) WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND active WITH element	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 11:04
-	8	"5148664"	"5150828"	"5205463"	"5710407"	"5717252"	"5803146"	"5812339"	"5896225").PN.	USPAT	2002/10/18 10:55
-	13	"4158262"	"4862245"	"4948754"	"5111711"	"5252853"	"5331200"	"5354487"	"5538920"	"5565379"	"5548924"	"5578526"	"5587336"	"5677587").PN.	USPAT	2002/10/18 10:59
-	14	5384491.URPN.	USPAT	2002/10/18 11:01
-	155	(((257/666).CCLS.) AND(metallization lead line bus) WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND encapsulate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 11:35
-	7	("5157182" | "5426246" | "5834837" | "5893216" | "5977613" | "5998877" | "6329715").PN.	USPAT	2002/10/18 11:08
-	1	"4546374".PN.	USPAT	2002/10/18 11:12
-	11	4546374.URPN.	USPAT	2002/10/18 11:12
-	29	5302849.URPN.	USPAT	2002/10/18 11:34
-	4	"4719500"	"5574287"	"5841024"	"5777351").PN.	USPAT	2002/10/18 11:41
-	8	6144101.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 13:56

-		6194821.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 13:44
-	9	("5482894" | "5574524" | "5668052" | "5796820" | "5843816" | "5861328" | "5865695" | "5994227" | "6144103").PN.	USPAT	2002/10/18 13:56
-	911	word with line with power with ground	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 14:53
-	121	.word with line with power with ground AND 257/\$.CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 14:53
-	9	6066515.URPN.	USPAT	2002/10/18 18:29
-	8	("5148964" | "5150828" | "5205463" | "5710457" | "5717252" | "5803246" | "5872338" | "5898225").PN.	USPAT	2002/10/18 18:37
-	803	(257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:39
-	32	((257/691).CCLS.) and power with lines with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:52
-	3	("5028983" | "5256996" | "5550406").PN.	USPAT	2002/10/18 18:43
-	4	5677570.URPN.	USPAT	2002/10/18 18:44
-	33	("4355456" | "4878096" | "4916519" | "4948754" | "4949150" | "4993305" | "4993618" | "5019721" | "5061985" | "5068801" | "5226582" | "5235212" | "5319224" | "5441917" | "5463255" | "5501337" | "5523626" | "5587607" | "5602420" | "5608245" | "5612570" | "5623154" | "5637920" | "5640048" | "5641978" | "5644166" | "5652467" | "5666008" | "5677570" | "5693984" | "5712508" | "5731634" | "5742100").PN.	USPAT	2002/10/18 18:47
-	759	(257/208).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:52
-	236	257/209.CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:52
-	1	(257/209.CCLS.) and power with lines with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:55
-		(257/209.CCLS.) and power with lines with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:55
-		(257/209.CCLS.) and power with line with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/18 18:57

-	3166	257/666 .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002 10 19 18:18
-	13	257/666 .ccls. and power with line with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 18:57
-	153	257/666 .ccls. and line with surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 19:11
-	111	power ground with line with surface and 257/S.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 19:12
-	88	((power ground)with line with surface and 257/S.ccls.) and lead with frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 19:26
-	2	5973554.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:22
-	2	6144100.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 16:35
-	4	("5182420" | "5367195" | "5369220" | "5734200").PN.	USPAT	2002/10/19 16:40
-	3166	257/666.CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 17:53
-	3	((257/666).CCLS.) and art with lead with frame with mounting with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 18:13
-	5	conventionally with mounting with pad with lead adj frame and (257/S).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 18:15
-	6	conventionally with mounting with pad with lead adj frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 18:16
-	11	conventionally with die with pad with lead adj frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/19 18:16